Type	L #	Hits	Search Text	DBs
1 BRS	L1	21560	multichip or multi adj chip or mcm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2 BRS	L2	270473 2	dicing or singulat$4 or cut$5 or saw$4 or laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3 BRS	L3	1712	1 same 2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4 BRS	L4	338	1 near4 2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5 BRS	L6	243	4 and (@ad < "20001222")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	L #	Hits	Search Text	DBs
6	BRS	L7	190901	wafer or substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	L8	300589	7 near8 (bond$4 or solder$4 or bga or ball near grid or mount$4 or attach$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	L9	42712	7 near8 (bond$4 or solder$4 or bga or ball near grid or mount$4 or attach$4) same (encapsulat$4 or resin or epoxy or infill$4 or underfill$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	L10	8488	9 and 2 and (packag$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	L11	1172	9 same 2 same (packag$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	L #	Hits	Search Text	DBs
11 BRS	L1 2	40263	(multiple or many or several or few) near2 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12 BRS	L1 3	19563	(multiple or many or several or few) adj2 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13 BRS	L1 4	60	13 same (bond$4 or solder$4 or bga or ball near grid or mount$4 or attach$4) same 2 same (packag$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14 BRS	L1 5	51	13 same (bond$4 or solder$4 or bga or ball near grid or mount$4 or attach$4) same 2 same (package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15 BRS	L1 6	13	15 and (@ad < "20001222")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	L #	Hits	Search Text	DBs
16 BRS	L17	497	(flipchip or flip adj chip or flip-chip) same (bond$4 or solder$4 or bga or ball near grid or mount$4 or attach$4) same 2 same (package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
17 BRS	L18	2517	(flipchip or flip adj chip or flip-chip) same (efficien$4 or throughput or through-put or through adj put or econom$4 or product$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
18 BRS	L19	217	(flipchip or flip adj chip or flip-chip) same (efficien$4 or throughput or through-put or through adj put or econom$4 or product$) same 2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
19 BRS	L20	48	17 same (efficien$4 or throughput or through-put or through adj put or econom$4 or product$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
20 BRS	L21	21	20 and (@ad < "20001222")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	L #	Hits	Search Text	DBs
21 BRS	L2 2	106	19 and (@ad < "20001222")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22 BRS	L2 3	85	22 not 21	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB